

Title (en)

PROCESS FOR REMOVING CONTAMINANT FROM A SURFACE AND COMPOSITION USEFUL THEREFOR

Title (de)

VERFAHREN FÜR DAS ENTFERNEN VON VERUNREINIGUNGEN VON DER OBERFLÄCHE UND DAFÜR NÜTZLICHE ZUSAMMENSETZUNGEN

Title (fr)

PROCEDE PERMETTANT D'ELIMINER DES CONTAMINANTS D'UNE SURFACE ET COMPOSITIONS UTILES A CET EFFET

Publication

EP 1196943 A4 20070117 (EN)

Application

EP 00936223 A 20000523

Priority

- US 0014181 W 20000523
- US 31881499 A 19990526
- US 53311400 A 20000322

Abstract (en)

[origin: WO0072363A1] Particulate and metal ion contamination is removed from a surface, such as a semiconductor wafer containing copper damascene or dual damascene features, employing aqueous composition comprising a fluoride containing compound; a dicarboxylic acid and/or salt thereof; and a hydroxycarboxylic acid and/or salt thereof.

IPC 8 full level

C11D 7/28 (2006.01); **H01L 21/02** (2006.01); **C11D 3/02** (2006.01); **C11D 3/20** (2006.01); **C11D 7/08** (2006.01); **C11D 7/10** (2006.01); **C11D 7/26** (2006.01); **C11D 11/00** (2006.01); **H01L 21/304** (2006.01); **H01L 21/3205** (2006.01); **H01L 21/321** (2006.01); **H01L 21/306** (2006.01)

CPC (source: EP KR)

C11D 3/042 (2013.01 - EP KR); **C11D 3/046** (2013.01 - EP KR); **C11D 3/2082** (2013.01 - EP KR); **C11D 3/2086** (2013.01 - EP KR); **C11D 7/08** (2013.01 - EP KR); **C11D 7/10** (2013.01 - EP KR); **C11D 7/265** (2013.01 - EP); **H01L 21/02074** (2013.01 - EP KR); **H01L 21/3212** (2013.01 - EP KR); **C11D 2111/22** (2024.01 - EP KR)

Citation (search report)

- [Y] WO 9921220 A1 19990429 - ONTRAK SYSTEMS INC [US]
- [Y] EP 0859404 A2 19980819 - MITSUBISHI MATERIAL SILICON [JP], et al
- See also references of WO 0072363A1

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DOCDB simple family (publication)

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